



**IRVINE SENSORS CORPORATION NEWS RELEASE**

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**FOR IMMEDIATE RELEASE**

**IRVINE SENSORS QUALIFIES LEAD-FREE STACKING PROCESS**  
**Applicable to wide range of stacked integrated circuit products**

COSTA MESA, CALIFORNIA – April 13, 2005 -- Irvine Sensors Corporation (Nasdaq: IRSN, Boston Stock Exchange: ISC) announced today that it has successfully qualified a proprietary manufacturing process for stacking integrated circuits (“ICs”) using lead-free solder. The global semiconductor industry is becoming increasingly focused on the elimination of potentially environmentally harmful substances, such as lead, in electronics. However, use of lead-free solder requires higher temperatures during manufacturing and more control of temperature and humidity conditions during storage.

John Carson, Irvine Sensors CEO, said, “We believe that we may be one of the first providers of stacked chip products that has qualified a lead-free manufacturing process. Although the industry does not have to make this transition overnight, our early qualification of a lead-free capability potentially opens the door to new customers for us and could start to increase our manufacturing volumes later this year.”

The lead-free solder qualified by Irvine Sensors is an industry standard. During qualification Irvine Sensors subjected stacked ICs to extensive thermal cycles, high temperature storage and temperature and humidity testing with a 100% success rate. Potential customers seeking more information on stacked lead-free products should contact Dan Michaels, Director of Operations, at [dmichaels@irvine-sensors.com](mailto:dmichaels@irvine-sensors.com).

Irvine Sensors Corporation, headquartered in Costa Mesa, California, is primarily engaged in the sale of stacked chip assemblies and miniaturized cameras and research and development related to high density electronics, miniaturized sensors, optical interconnection technology, high speed routers, image processing and low-power analog and mixed-signal integrated circuits for diverse systems applications.

**Safe Harbor Statement under the Private Securities Litigation Reform Act of 1995:** This news release may contain forward-looking statements based on our current expectations, estimates and projections about our industry, management's beliefs, and certain assumptions made by us. Words such as "anticipates," "expects," "projects", "intends," "plans," "believes," "seeks," "estimates," "may," "will", "potentially" and variations of these words or similar expressions are intended to identify forward-looking statements. These statements include, but are not limited to, our expectations regarding potential demand for lead-free semiconductor parts and our ability to respond to such demand, if it is present. Such statements speak only as of the date hereof and are subject to change. We undertake no obligation to revise or update publicly any forward-looking statements for any reason. These statements are not guarantees of future performance and are subject to certain risks, uncertainties and assumptions that are difficult to predict. Therefore, our actual results could differ materially and adversely from those expressed in any forward-looking statements as a result of various factors.

Important factors that may cause such a difference include, but are not limited to, our ability to achieve design wins for and market acceptance of our stacked lead-free products; the ability of our potential customers to achieve market acceptance of their products incorporating our lead-free technology; the ability of our sources of supply to meet volume production needs for lead-free products, should such needs emerge; our ability to raise additional capital to meet potential tooling requirements associated with volume production of lead-free products; our ability to control costs and expenses; the potential unforeseen impact of product offerings from competitors; and general economic and political conditions and specific conditions in the markets we address, particularly as it might effect the status of contract manufacturing sources that we would likely have to employ to manufacture lead-free products. Further information on Irvine Sensors Corporation, including additional risk factors that may affect our forward looking statements, is contained in our Annual Report on Form 10-K, our Quarterly Reports on Form 10-Q, our Current Reports on Form 8-K and our other SEC filings that are available through the SEC's website ([www.sec.gov](http://www.sec.gov)).